Compliant with IEC 62474/ D9.00

Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: P (D6X) 016 PDIP (Small Outline300in) Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				JEDEC 97 Product Marking and/or Pkg. Labeling e3
		"Contained In"	% Total			887.93	(mg) Total	Mold Compound	% ot Total Weight	
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm		,		=====	i
Fused Silica	60676-86-0	Mold Compound	57.456	639.313	574,560		Fused Silica	60676-86-0	72.00	
Metal Hydro Oxide	Trade Secret	Mold Compound	8.778	97.673	87,780		Metal Hydro Oxide	Trade Secret	11.00 7.00	
Epoxy Resin	Trade Secret	Mold Compound	5.586	62.155	55,860		Epoxy Resin	Trade Secret		
Phenol Resin SiO2	Trade Secret 14808-60-7	Mold Compound	5.586 1.995	62.155 22.198	55,860 19,950		Phenol Resin SiO2	Trade Secret	7.00 2.50	
Carbon Black	1333-86-4	Mold Compound Mold Compound	0.399	4.440	3,990			14808-60-7		
							Carbon Black	1333-86-4	0.50	
Copper	7440-50-8	Lead Frame	10.031	111.620	100,314			Total		
Iron	7439-89-6	Lead Frame	0.247	2.746	2,468	116.83	(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.200	2.226	2,000		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.013	0.146	131		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.009	0.096	87		Silver	7440-22-4	1.91	
Silver	7440-22-4	Die Attach	0.563	6.259	5,625		Zinc	7440-66-6	0.13	
Diester Resin	94-80-4	Die Attach	0.113	1.252	1,125		Phosphorous	7723-14-0	0.08	
Functionalized Urethane Resin	72869-86-4	Die Attach	0.038	0.417	375			Total	100.00	
Epoxy Resin	9003-36-5	Die Attach	0.019	0.209	188	8.35	(mg) Total	Die Attach	% of Total Weight	0.75
Epoxy Resin	13561-08-5	Die Attach	0.019	0.209	188		Silver	7440-22-4	75.00	
Silicon	7440-21-3	Chip (Die)	7.500	83.453	75,000		Diester Resin	94-80-4	15.00	
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.197	2.186	1,965	Fun	ctionalized Urethane Resir	72869-86-4	5.00	
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.004	0.039	35		Epoxy Resin	9003-36-5	2.50	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	13.909	12,500		Epoxy Resin	13561-08-5	2.50	
	<u> </u>	TOTALS:	100.000	1,112.700	1,000,000		1 7	Total	100.00	ш
	1 1127	g Total Mass								
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)						83.45	Total (mg)	Chip (Die)	% of Total Weight	7.5
			011) and 2015/	/863/EU (31 Ma	rch 2015)	83.45	Total (mg) Doped Silicon	Chip (Die) 7440-21-3	% of Total Weight	7.5
	n (zero)	s: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2	011) and 2015/	/863/EU (31 Ma	rch 2015)	83.45	, ,		100	
nd 2002/53/EC (End-of-Life Vehicles (ELV) without exemption ompliance with the above EU Directives has been verified via a chemical substance is absent from the list above, the cher corporated's knowledge and belief as of the date of this doc	n (zero) a internal design contro mical substance is NOT cument, there is no creo	s: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2	best of Microc	hip Technolog	Iy	2.23	, ,	7440-21-3	100	
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and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption compliance with the above EU Directives has been verified via a chemical substance is absent from the list above, the cher acorporated's knowledge and belief as of the date of this doc elow the threshold of regulatory concern for any regulatory soloding compounds used by Microchip meet the UL94 V0 flar tru://ul.com/global/eng/pages/offerings/industries/chemicals. he protective "tubes" in which the specific product is shippereels" may be made from PVC plastic. Ilicrochip Technology Incorporated believes the information in riginal packing materials is true and correct to the best of its of accuracy of data in this form because it has been compile rotected from disclosure as trade secrets and some informate.	n (zero) a internal design contre mical substance is NOT zument, there is no cree scheme world-wide. mmability standard for /plastics/ ed are made from polyv in this form concerning is knowledge and belief, ed based on the ranges tion may not have been if anticipated significan	5: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2 ols, supplier declarations, and /or analytical test data. Fan intentional ingredient in the semiconductor device and, to the lidible reason to believe that the unavoidable impurity concentration plastics. You can access the UL iQTM family of databases to obtain	best of Microc of the chemic n a test report a packing slip or ated's semicon ted cannot gue suppliers. Supp nformation is p	thip Technolog al substance, i at n the outer box anductor device arantee the con plier informatic provided only a	if any, is not and certain s in their npleteness on is often as estimates		Doped Silicon (mg) Total Copper	7440-21-3 Total Wire Bond Copper palladium coated (CuPd) 7440-50-8	100 100.00 % of Total Weight 98	0.2
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